

LEAD PROTECTIVE COATING COMPOSITION, PROCESS  
AND STRUCTURE THEREOF

Abstract of the Disclosure

5 An electronic package assembly where a low profile integrated circuit chip  
package is soldered to an organic (e.g., epoxy resin) substrate, e.g., a printed circuit  
board or card, the projecting conductive leads of the integrated circuit chip package and  
the solder which substantially covers these leads (and respective conductors on the  
substrate) having been substantially covered with ultraviolet photocured encapsulant  
material (e.g., polymer resin) to provide reinforcement for the solder-lead connections.  
10 The encapsulant material is dispensed about the solder and lead joints following solder  
reflow and solidification so as to substantially surround the solder and any portions of  
the leads not covered with solder.